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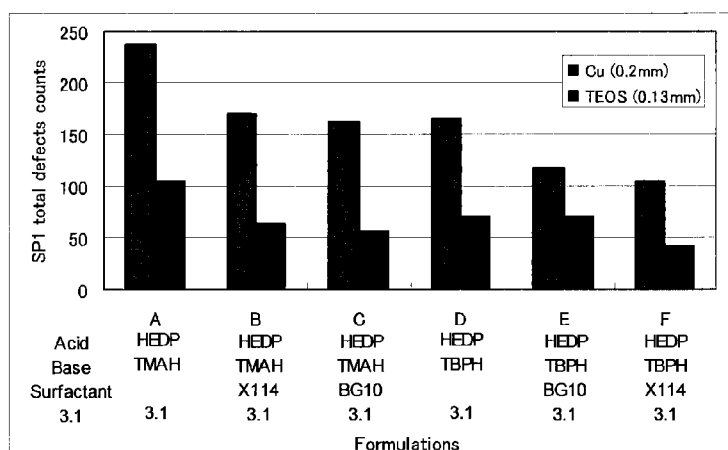


Fig. 1

(57) Abstract: A semiconductor processing composition and method for cleaning semiconductor wafers post chemical mechanical polishing comprising a phosphorous base and optionally at least one surfactant.